

Claims

- [c1] What is to claimed is:
- 1.A holding apparatus for an optical integration rod, comprising a holder, installed outside of said optical integration rod, wherein a thermal conductivity material is filled in between said holder and said optical integration rod.
 - [c2] 2.The holding apparatus according to claim 1, wherein said holder is a heat sink substrate.
 - [c3] 3.The holding apparatus according to claim 2, wherein said heat sink substrate is a high heat conduction coefficient material.
 - [c4] 4.The holding apparatus according to claim 2, further comprising fins which are disposed on said heat sink substrate.
 - [c5] 5.The holding apparatus according to claim 4, wherein said fins can be disposed at one side of said heat sink substrate at least.
 - [c6] 6.The holding apparatus according to claim 1, wherein said holder is a hollow column.

- [c7] 7.The holding apparatus according to claim 1, further comprising at least a glue filling hole is disposed at the surface of said holder.
- [c8] 8.The holding apparatus according to claim 1, further comprising one end of a heat pipe is connected to said holder and another end thereof is connected to a heat sink apparatus.
- [c9] 9.The holding apparatus according to claim 8, wherein said heat sink apparatus is a heat sink sheet.